



Product Change Notification / RMES-10YAUB493

Date:

11-Jul-2022

Product Category:

Microprocessors

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4898 and 4898.001 Final Notice: Qualification of a new die size for Die # 2 for selected catalog part numbers (CPN) SAM9X60D1G-I/4FB, SAM9X60D1GT-I/4FB, SAM9X60D5M-I/4FB, SAM9X60D5MT-I/4FB available in 233L TFBGA (14x14x1.2mm) and U2 component for selected catalog part number (CPN) SAM9X60D1G-I/LZB available in 152L MODULE (28x28x2.4mm) packages.

Affected CPNs:

[RMES-10YAUB493_Affected_CPN_07112022.pdf](#)

[RMES-10YAUB493_Affected_CPN_07112022.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of a new die size for Die # 2 for selected catalog part numbers (CPN) SAM9X60D1G-I/4FB, SAM9X60D1GT-I/4FB, SAM9X60D5M-I/4FB, SAM9X60D5MT-I/4FB available in 233L TFBGA (14x14x1.2mm) and U2 component for selected catalog part number (CPN) SAM9X60D1G-I/LZB available in 152L MODULE (28x28x2.4mm) packages.

Pre and Post Change Summary:

	Pre Change	Post Change
Die Size change for Die # 2 and U2 component	With change in die size. See Pre and Post Change Summary for comparison.	

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve manufacturability by qualifying a new die size for Die # 2 for selected catalog part numbers (CPN) SAM9X60D1G-I/4FB, SAM9X60D1GT-I/4FB, SAM9X60D5M-I/4FB, SAM9X60D5MT-I/4FB available in 233L TFBGA (14x14x1.2mm) and U2 component for selected catalog part number (CPN) SAM9X60D1G-I/LZB available in 152L MODULE (28x28x2.4mm) packages.

Change Implementation Status:In Progress

Estimated First Ship Date:

July 15, 2022 (date code: 2229)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	July 2022				
Workweek	2 8	2 9	3 0	3 1	3 2
Qual Report Availability		x			
Final PCN Issue Date		x			
Estimated Implementation Date		x			

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:July 11, 2022: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_RMES-10YAUB493_Pre and Post Change_Summary.pdf](#)

[PCN_RMES-10YAUB493_Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

SAM9X60D1G-I/4FB

SAM9X60D1GT-I/4FB

SAM9X60D5M-I/4FB

SAM9X60D5MT-I/4FB

SAM9X60D1G-I/LZB